

 D.G.M.E.	DG20N120	版本号: V1.0
	绝缘栅双极型晶体管	

产品概述

IGBT既有功率MOSFET输入阻抗高, 控制功率小, 易于驱动, 控制简单的特点, 又有双极晶体管的导通电压低, 通态电流大, 损耗小的显著优点。在提倡节能减排、低碳经济的时代, 具备节能效率高, 便于规模化生产等优点的IGBT已成为功率半导体市场发展的主流技术。

产品特点

- 采用NPT技术
- 高开关速度: $t_f = 170\text{ns}$
- 低饱和压降: $V_{CE(sat)} = 2.15\text{V} @ I_c=20\text{A}$
- 高输入阻抗
- 热稳定性好

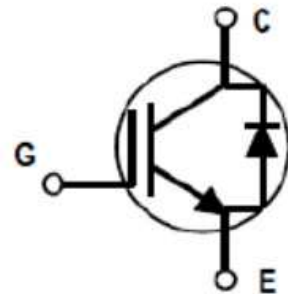
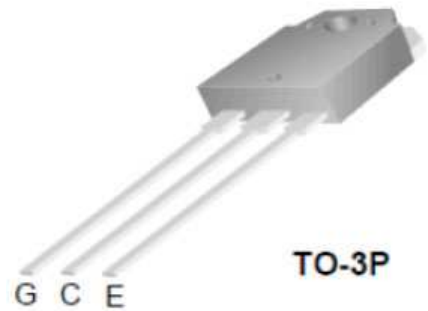
应用领域

主要用于感应加热领域, 如电磁炉。

特征参数

符号	额定值	单位
$V_{(BR)CES}$	1200	V
I_c	20	A
$V_{CE(sat)}$	2.2	V

封装: TO-3P



极限值

除非另有规定, $T_a=25^\circ\text{C}$

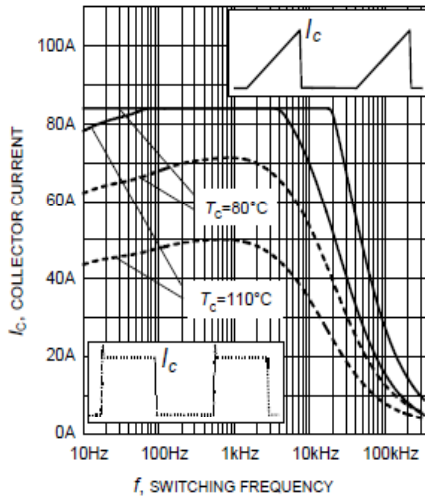
参数名称	符号	额定值	单位
集电极-发射极击穿电压	V_{CE}	1200	V
连续集电极	I_c	20	A
脉冲集电极电流	I_{cpuls}	50	A
栅-发射极电压	V_{GE}	± 30	V
耗散功率 $T_c=25^\circ\text{C}$	P_D	170	W
工作温度范围	T_J	-55 to +150	$^\circ\text{C}$
贮存温度范围	T_{STG}	-55 to +150	$^\circ\text{C}$

电参数

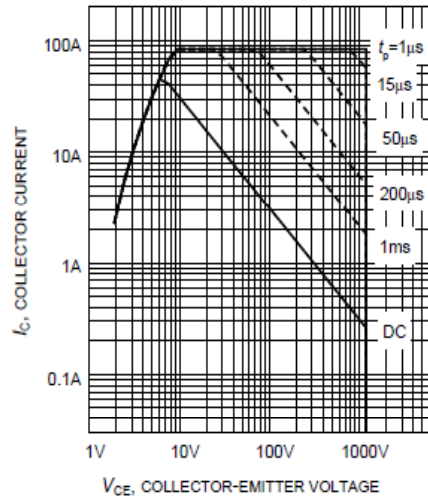
除非另有规定, $T_a=25^{\circ}\text{C}$

参数名称	符号	测试条件	规范值			单位
			最小	典型	最大	
$V_{(BR)CES}$	集电极-发射极击穿电压	$V_{GE}=0$ $I_C=1000\mu\text{A}$	1200			V
I_{CES}	集电极-发射极泄漏电流	$V_{GE}=0$ $V_{CE}=1200\text{V}$			180	μA
I_{GSS}	栅极-发射极泄漏电流	$V_{CE}=0$ $V_{GE}=20\text{V}$			100	nA
$V_{GE(th)}$	开启电压	$V_{GE}=V_{CE}$, $I_D=600\mu\text{A}$	3.0		6.0	V
$V_{CE(sat)}$	集电极-发射极饱和压降	$V_{GE}=15\text{V}$, $I_C=20\text{A}$		2.2	2.8	V
C_{iss}	输入电容	$V_{CE}=25\text{V}$, $V_{GE}=0$, $f=1\text{MHz}$		1350	1650	pF
C_{oss}	输出电容			100	120	pF
C_{rss}	反向恢复电容			65	80	pF
Q_g	栅电荷	$V_{CC}=960\text{V}$ $I_C=20\text{A}$ $V_{GE}=15\text{V}$		186	240	nC
$t_d(on)$	导通延时	$V_{CC}=800\text{V}$, $I_C=20\text{A}$, $R_G=33\ \Omega$ 感性负载		38	50	ns
t_r	上升时间			26	40	ns
$t_d(off)$	关断延时			240	350	ns
t_f	下降时间			170	230	ns
E_{on}	开启能量			2.2	2.6	mJ
E_{off}	关断能量			0.92	1.2	mJ
$t_d(on)$	导通延时	$V_{CC}=800\text{V}$, $I_C=20\text{A}$, $R_G=33\ \Omega$ $T_C=150^{\circ}\text{C}$ 感性负载		40	55	ns
t_r	上升时间			28	45	ns
$t_d(off)$	关断延时			242	365	ns
t_f	下降时间			178	250	ns
E_{on}	开启能量			2.4	2.7	mJ
E_{off}	关断能量			0.98	1.3	mJ
V_{FM}	二极管正向压降	$I_F=20\text{A}$		1.8	2.5	V
t_{rr}	二极管反向恢复时间	$I_F=20\text{A}$ $di/dt=200\text{A}/\mu\text{s}$		230	330	ns
I_{rr}	二极管反向峰值电流			29	40	A
Q_{rr}	二极管反向恢复电荷			2930	6750	nC

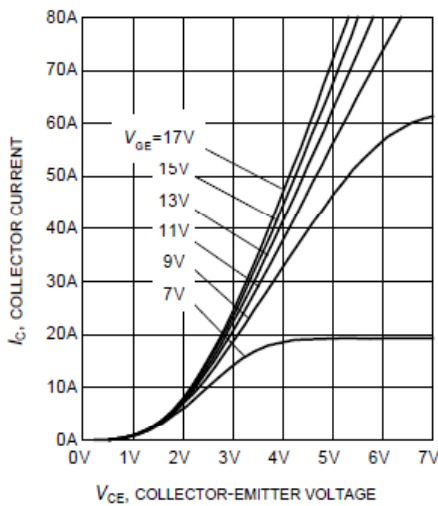
典型特性曲线



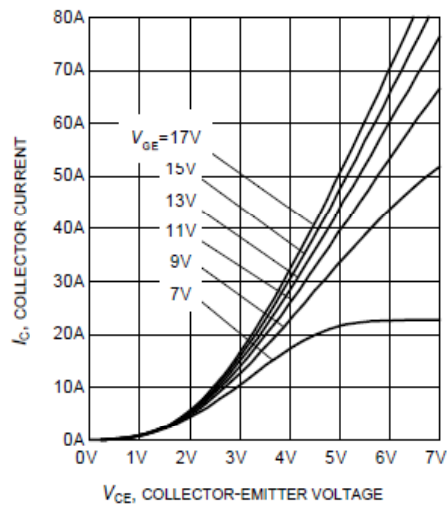
集电极电流与开关频率的关系曲线



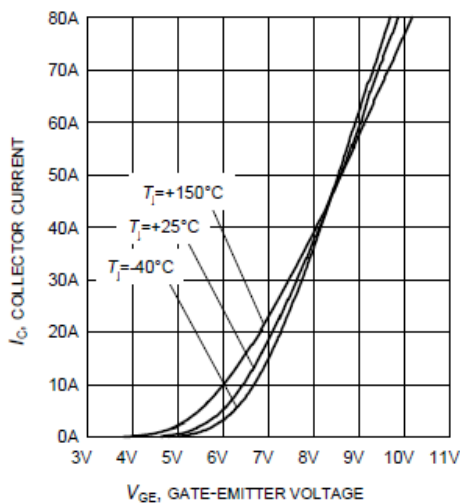
安全工作区



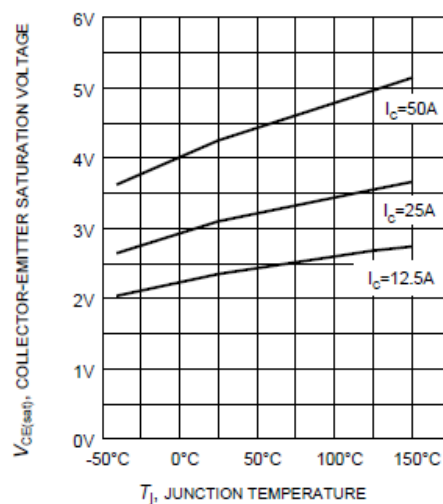
输出特性曲线 ($T_C=25^\circ\text{C}$)



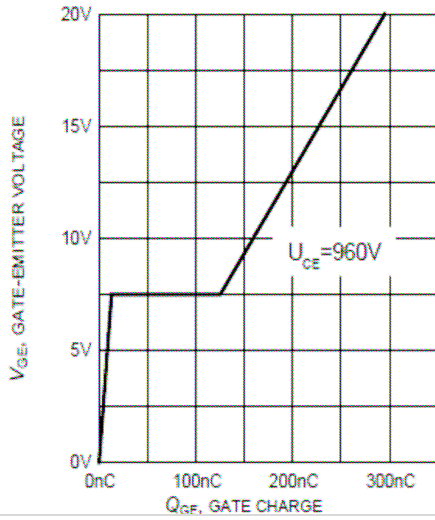
输出特性曲线 ($T_C=150^\circ\text{C}$)



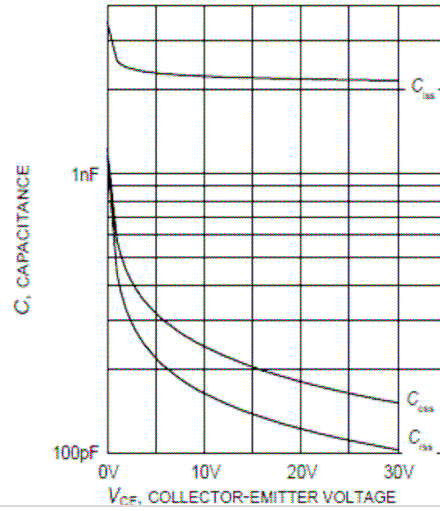
传输特性曲线



集电极-发射极饱和压降与结温的关系曲线



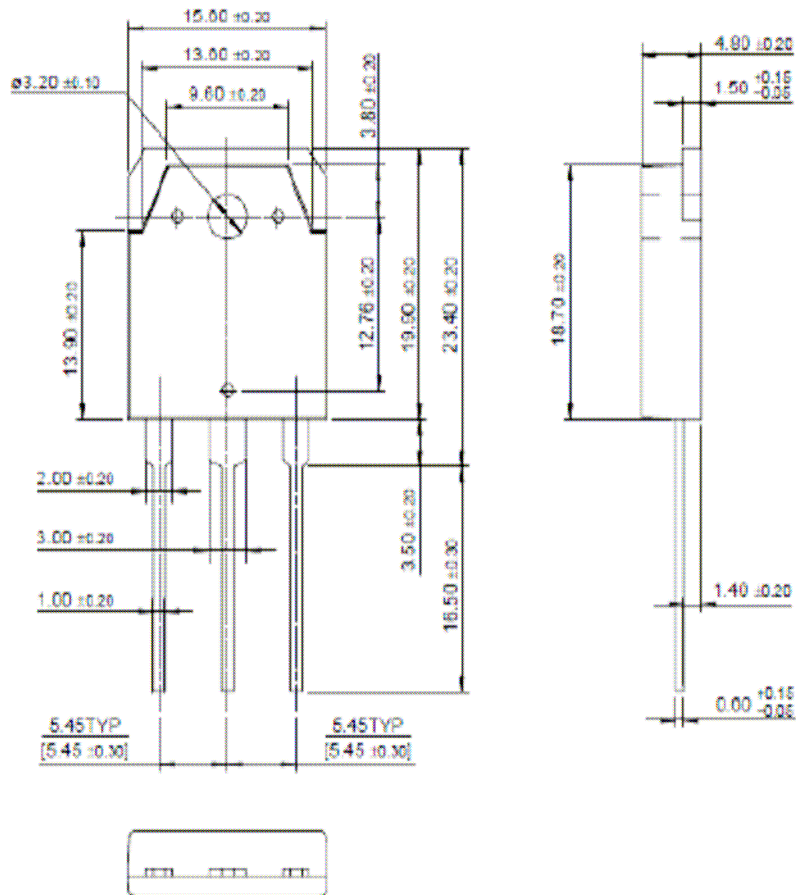
栅电荷特性曲线
($I_C=15A$)



电容与集电极-发射极电压关系曲线
($V_{GE}=0V$ $f=1MHz$)

附录：封装尺寸

TO-3P



 D. G. M. E.	DG20N120	Version No. : V1.0
	IGBT	

General Description

IGBT has been the major switching device in power electronic applications as it has the merits of both power bipolar and power MOSFET. It has been widely used in high voltage field, which ranges from industrial areas such as inverters, high voltage switch, and motor operation to PDP or home appliance.

Features

- Employing NPT technology
- High speed switching: $t_f = 170\text{ns}$
- Low saturation voltage: $V_{CE(sat)} = 2.15\text{V} @ I_c=20\text{A}$
- High input impedance

Applications

Induction Heating

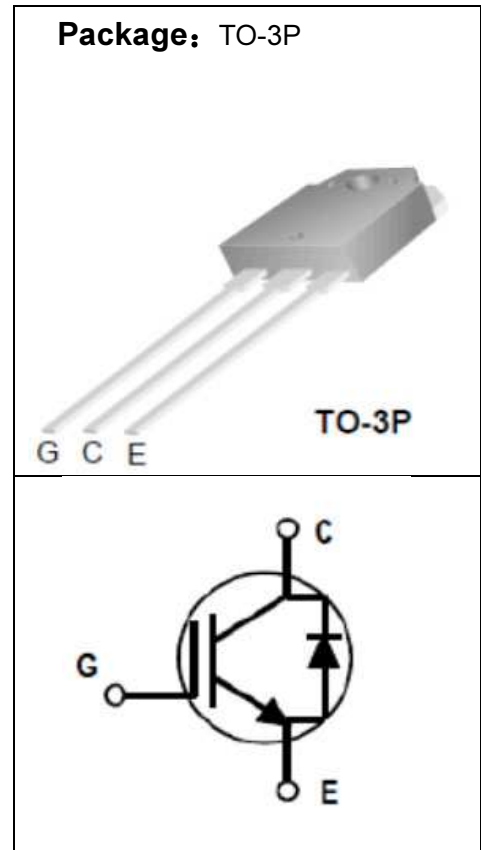
Characteristic parameter

SYMBOL	Value	Unit
$V_{(BR)CES}$	1200	V
I_c	20	A
$V_{CE(sat)}$	2.2	V

Maximum Ratings

$T_c=25^\circ\text{C}$, unless otherwise specified

PARAMETER	SYMBOL	Value	Unit
Collector-emitter voltage	V_{CE}	1200	V
DC collector	I_c	20	A
Pulsed collector current	I_{cpuls}	50	A
Gate-emitter voltage	V_{GE}	± 30	V
Power dissipation $T_c=25^\circ\text{C}$	P_D	170	W
Operating junction temperature	T_J	-55 to +150	$^\circ\text{C}$
Storage temperature	T_{STG}	-55 to +150	$^\circ\text{C}$

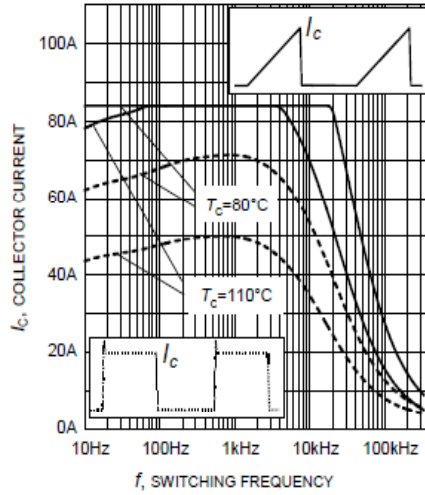


Electrical Characteristic

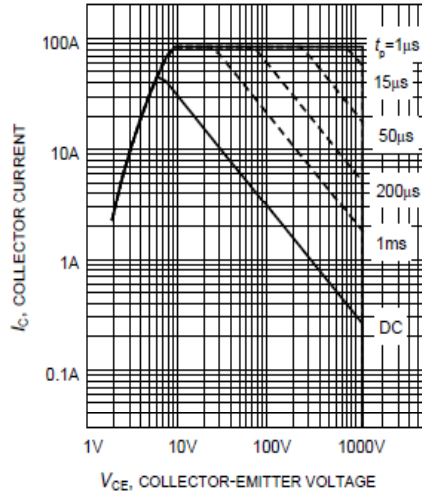
at Tc=25°C, unless otherwise specified

PARAMETER	SYMBOL	Conditions	Value			Unit
			Min.	Typ.	Max.	
V _{(BR)CES}	Collector-emitter breakdown voltage	V _{GE} =0 I _C =1000uA	1200			V
I _{CES}	Zero gate voltage collector current	V _{GE} =0 V _{CE} =1200V			180	uA
I _{GSS}	Gate-emitter leakage current	V _{CE} =0 V _{GE} =20V			100	nA
V _{GE(th)}	Gate-emitter threshold voltage	V _{GE} =V _{CE} , I _D =600uA	3.0		6.0	V
V _{CE(sat)}	Collector-emitter saturation voltage	V _{GE} =15V, I _C =20A		2.2	2.8	V
C _{iss}	Input capacitance	V _{CE} =25V, V _{GE} =0, f=1MHz		1350	1650	pF
C _{oss}	output capacitance			100	120	pF
C _{rss}	Reverse transfer capacitance			65	80	pF
Q _g	Gate charge	V _{CC} =960V I _C =20A V _{GE} =15V		186	240	nC
td(on)	Turn-on delay time	V _{CC} =800V, I _C =20A, R _G =33 Ω Inductive load		38	50	ns
tr	Rise time			26	40	ns
td(off)	Turn-off delay time			240	350	ns
tf	Fall time			170	230	ns
E _{on}	Turn-on energy			2.2	2.6	mJ
E _{off}	Turn-off energy			0.92	1.2	mJ
td(on)	Turn-on delay time	V _{CC} =800V, I _C =20A, R _G =33 Ω T _C =150°C Inductive load		40	55	ns
tr	Rise time			28	45	ns
td(off)	Turn-off delay time			242	365	ns
tf	Fall time			178	250	ns
E _{on}	Turn-on energy			2.4	2.7	mJ
E _{off}	Turn-off energy			0.98	1.3	mJ
V _{FM}	Diode forward voltage	I _F =20A		1.8	2.5	V
trr	Diode reverse recovery time	I _F =20A di/dt=200A/ us		230	330	ns
I _{rr}	Diode peak reverse recovery current			29	40	A
Q _{rr}	Diode reverse recovery charge			2930	6750	nC

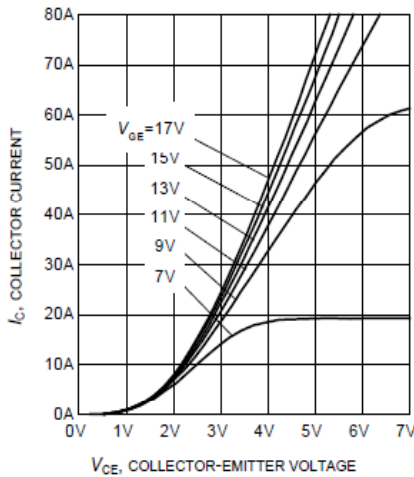
Characteristic curves



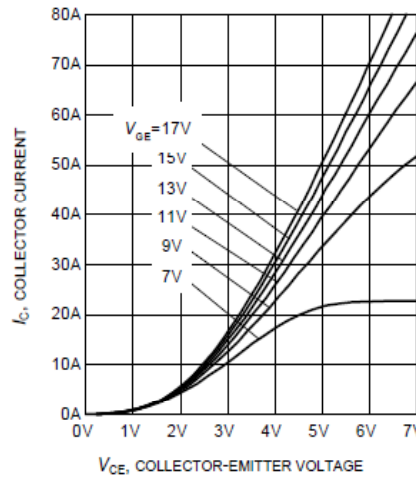
Collector current as a function of switching frequency



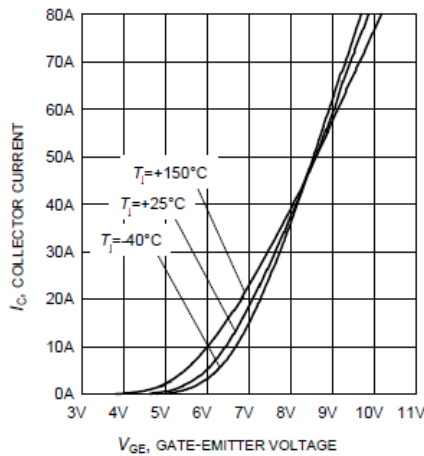
Safe operating area



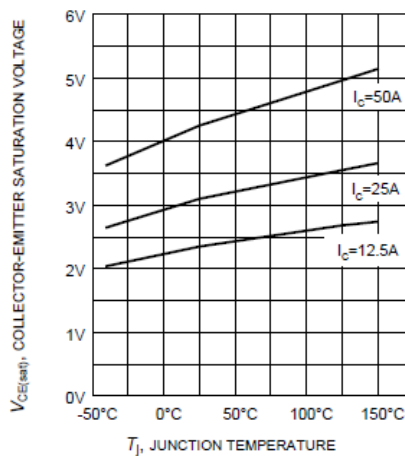
Typical output characteristic ($T_c = 25^\circ\text{C}$)



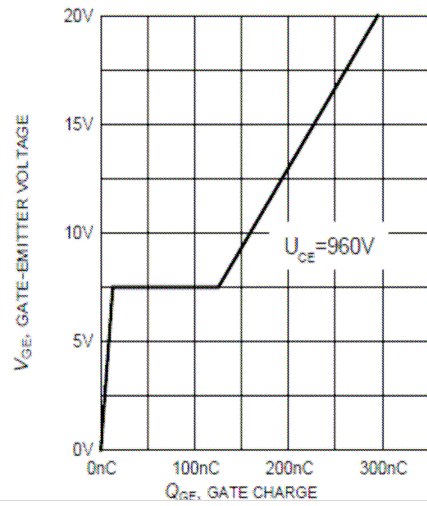
Typical output characteristic ($T_c = 150^\circ\text{C}$)



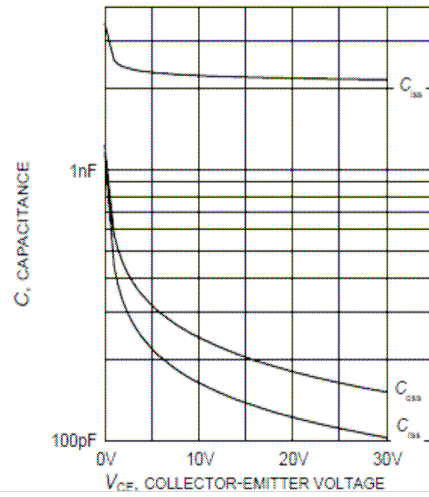
Typical transfer characteristic



Typical collector-emitter saturation voltage as a function of junction temperature



Typical gate charge
($I_C=15A$)



typical capacitance as a function of
collector-emitter voltage
($V_{GE}=0V$ $f=1MHZ$)

Package Dimension

TO-3P

